

ABSTRACT OF THE DISCLOSURE

THIS SHEET HAS BEEN
REPLACED

A method for manufacturing a holding tray for chip components is provided in which residual stress in the elastic member does not affect accuracy in machining of the hole and a metallic mold is not required. The method for manufacturing a holding tray for chip components having a plurality of holding holes comprises the steps of preparing a hard substrate including a frame portion, a flat board portion unitarily formed with the inner peripheral surfaces of the frame portion, and a plurality of through-holes formed on the flat board portion; forming an elastic member in a region surrounded by the frame portion of the hard substrate to cure it; and making therethrough holding holes smaller than the through-holes by means of laser machining at positions corresponding to those of the through-holes on the elastic member after curing of the elastic member.

This Sheet Has Been Replaced

